



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Standard**

Number of Positions: **168**

Module Orientation: **25°**

Centerline (Pitch): **1.27 mm [ .05 in ]**

Row-to-Row Spacing: **1.6 mm [ .063 in ]**

## Features

### Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Standard

### Configuration Features

Number of Keys	2
Number of Bays	3
Number of Rows	2
Number of Positions	168
Module Orientation	25°

### Electrical Characteristics

DRAM Voltage	3.3 V
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### Body Features

Retention Post Location	Center
Latch Material	High Temperature Nylon
PCB Retention Feature Material	Phosphor Bronze
Connector Profile	Low
Module Key Type	Key1= Center / Key2= Center
Ejector Location	Both Ends
Ejector Material	High Temperature Nylon
Ejector Type	Standard

### Contact Features

Contact Underplating Material	Nickel
Socket Style	DIMM 2P
Contact Mating Area Plating Material Thickness	.76 $\mu\text{m}$ [29.92 $\mu\text{in}$ ]
PCB Contact Termination Area Plating Material Thickness	3.81 $\mu\text{m}$ [150 $\mu\text{in}$ ]
Contact Mating Area Plating Material	Gold (Au)
Memory Socket Type	Memory Card
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin

### Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	2.6 mm[.102 in]

### Mechanical Attachment

PCB Mount Retention	With
Mount Angle	Right Angle
PCB Mount Retention Type	Boardlock
Mating Alignment Type	Center
Mating Alignment	With

### Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	1.27 mm[.05 in]

### Dimensions

Center Retention Hole Diameter	2.4 mm[.094 in]
Profile Height from PCB	12.15 mm[.47 in]
Row-to-Row Spacing	1.6 mm[.063 in]

### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	32
Packaging Method	Box & Tray, Tray

## Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: DEC 2013 (151) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

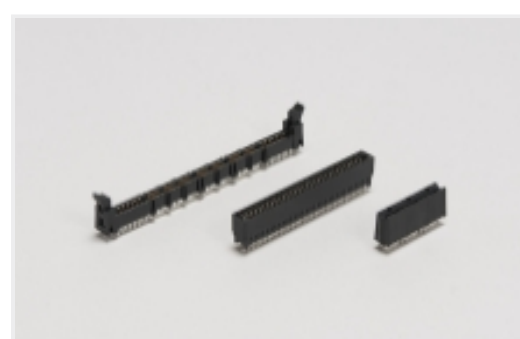
### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

## Also in the Series | AMP-METRIMATE



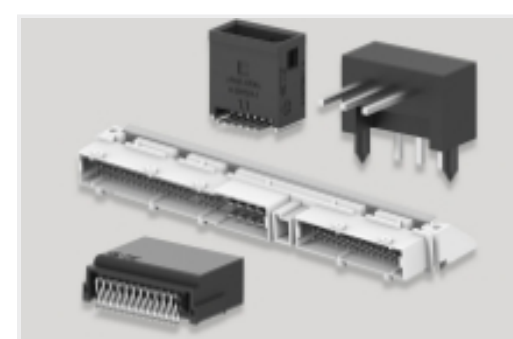
Board-to-Board Headers & Receptacles(1)



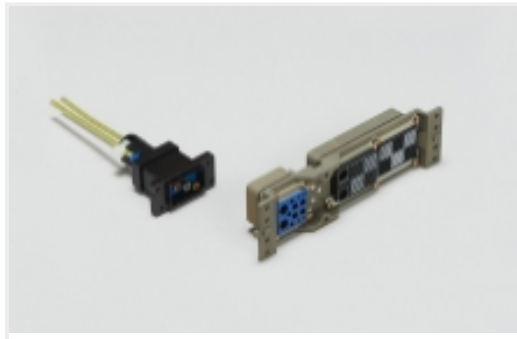
Card Edge Power Connectors(1)



Connector Hardware(1)



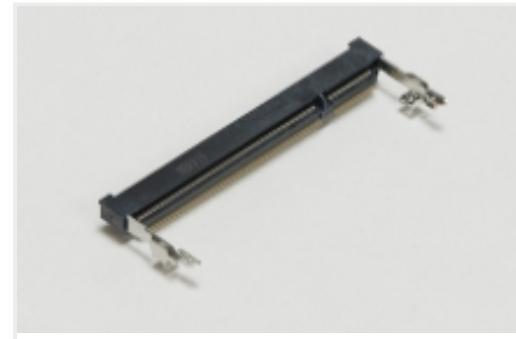
PCB Headers & Receptacles(1)



Rack & Panel Connectors(1)



Rectangular Power Connectors(3)

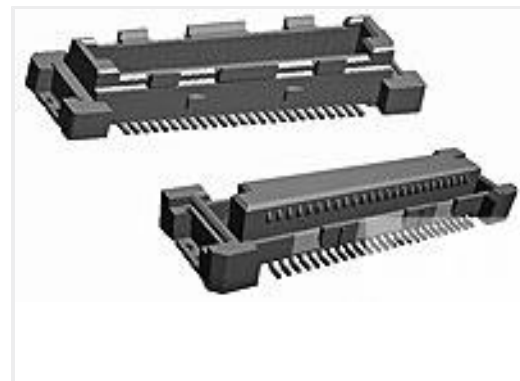


SO DIMM Sockets(12)

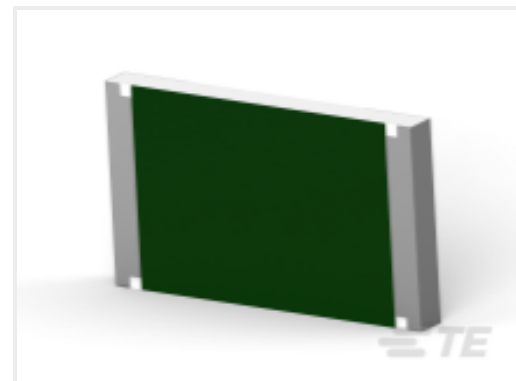
## Customers Also Bought



TE Part #NB18922001  
RNF-100-1/16-YO-STK



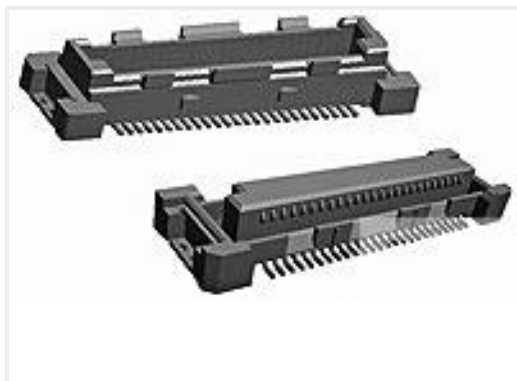
TE Part #1-5353729-0  
.6FHR04H,280,B,GIG,08/Sn,ST,NSYes



TE Part #2176406-9  
3560 2R2 1%



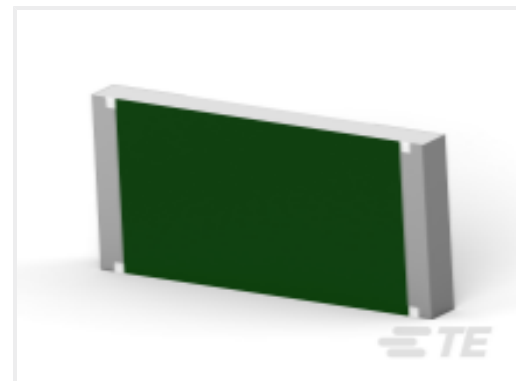
TE Part #1-1879128-4  
RN 0402 604R 0.1% 10PPM 1K RL



TE Part #1-5353727-0  
.6FHP08H,280,B,GIG,08/Sn,ST,NSYes



TE Part #2118721-4  
STD SHIELD COVER, AL-38.60X25.90X2.00MM



TE Part #2176403-2  
3550 1R1 1%



TE Part #2085958-1  
ICCON,SIZE 4,LOCKING PIN ASSEMBLY



TE Part #5-535512-2  
112 MODII HORZ DR CE EESS .100

## Documents

### CAD Files

3D PDF

English

### Customer View Model

[ENG\\_CVM\\_5390195-4\\_B.3d\\_igs.zip](#)

English

### Customer View Model

[ENG\\_CVM\\_5390195-4\\_B.3d\\_stp.zip](#)



English

Customer View Model

[ENG\\_CVM\\_5390195-4\\_B.2d\\_dxf.zip](#)

English

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